Layer Order
1. Signal 1, Comp. Side
2. Power
3. Signal 2
4. Signal 3
5. Ground
6. Signal 4, Solder Side

Board Characteristics:
1. All dimensions are given in inches unless specified otherwise.
2. Material FR4 - Tg > 170°C.
3. Minimum trace width 0.007" on all layers.
4. Minimum Clearance 0.006" on all layers.
5. 1 oz copper for all Trace and Power Layers.
6. Apply ENTEC or equivalent Organic Coating over bare copper.
7. Apply Solder Mask over bare copper.
8. Drill the Top and Bottom of board on the solder side to a thickness of 0.062" +/- 0.008".
9. Silk-screen on Component and Solder Sides.
10. 45 degree chamfer.
11. Hole diameter tolerances: +/- 0.002" unless specified otherwise.
12. Interlayer spacing: as specified.

This is a press fit technology through hole with the following specs:
12-1. Finished hole size: 0.6mm +/- 0.05mm
12-2. Drilled hole size: 0.7mm +/- 0.02mm
12-3. Thickness of through hole plating: min 25μm Cu
12-4. Inside through hole: OSP with 0.12 - 0.15μm.